

MDB6S / MDB8S / MDB10S

1 A, MicroDIP, Single-Phase Bridge Rectifiers

Features

- Low Package Profile: 1.60 mm (max)
- Small Area Requirements: 35 mm²
- Efficient V_F
 - 0.935 V (Typ) at 1 A
 - 1.165 V (Typ) at 5 A
- $I_F(AV) = 1.0$ A
- $I_{FSM} = 30$ A
- Glass Passivated Junctions
- RoHS Compliant
- Halogen Free
- UL Certification: E352360

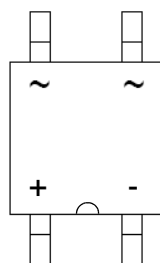
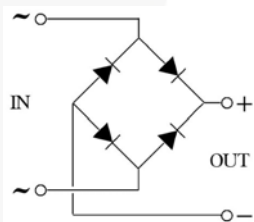
Description

With the ever pressing need to improve power supply efficiency and reliability, the MDBxS family is focused on offering a best in class small form factor combined with best in class efficient rectifier performance.

The “S” family offers industry leading balance of efficiency, size, and cost. They offer designers improved efficiency by achieving an industry leading V_F of 0.935 V Typ. at 1 A 25 °C, and a V_F of 1.165 V Typ. at 5 A 25 °C. These lower V_F values offer roughly a 5% efficiency improvement over measured competitive same form factor devices. This lower V_F vs. competitive devices results in cooler and more efficient power supply operation.

The design supports a 30 A I_{FSM} rating to absorb high surge currents and offers rated breakdown voltages up to 1000 V.

Finally, the MDBxS family achieves all this in a small form factor micro-dip package - offering a max height of 1.6 mm, and requiring only 35 mm² of board space.



Micro DIP

Ordering Information

Part Number	Marking	Package	Packing Method
MDB6S	MDB6S	Micro DIP	Tape and Reel
MDB8S	MDB8S		
MDB10S	MDB10S		

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Value			Units
		MDB6S	MDB8S	MDB10S	
V_{RRM}	Maximum Repetitive Peak Reverse Voltage	600	800	1000	V
V_{RMS}	Maximum RMS Voltage	420	560	700	V
V_{DC}	Maximum DC Blocking Voltage	600	800	1000	V
$I_{F(AV)}$	Average Rectified Forward Current ⁽¹⁾	1.0			A
I_{FSM}	Peak Forward Surge Current ⁽²⁾	30			A
I^2t	I^2t Rating for fusing ($t < 8.3$ ms)	3.735			A^2S
T_J	Operating Junction Temperature Range	-55 to +150			$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to +150			$^\circ\text{C}$

Notes:

- 60 Hz sine wave, R-load, $T_A = 25^\circ\text{C}$ on FR-4 PCB.
- 60 Hz sine wave, Non-repetitive 1 cycle peak value, $T_J = 25^\circ\text{C}$.

Thermal Characteristics⁽³⁾

Symbol	Parameter	Typ.	Units	
$R_{\theta JA}$	Thermal Resistance, Junction-Ambient	Measurement with Dual Dice	250	$^\circ\text{C}/\text{W}$
		Measurement with Single Die	150	$^\circ\text{C}/\text{W}$
ψ_{JL}	Thermal Characterization, Junction to Lead	Measured at Anode pin	57	$^\circ\text{C}/\text{W}$
		Measured at Cathode pin	15	$^\circ\text{C}/\text{W}$

Note:

- Device mounted on FR-4 PCB with board size = 76.2 mm x 114.3 mm (JE51-3 standards).

Electrical Characteristics

Values are at $T_A = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Test condition	Value	Units
V_F	Maximum Forward Voltage	$I_F = 1$ A, Pulse measurement, Per diode	1.1	V
I_R	Maximum Reverse Current	At V_{RRM} , Pulse measurement, Per diode	10	μA
C_J	Typical Junction Capacitance	$V_R = 4$ V, $f = 1$ MHz	10	pF

Typical Performance Characteristics

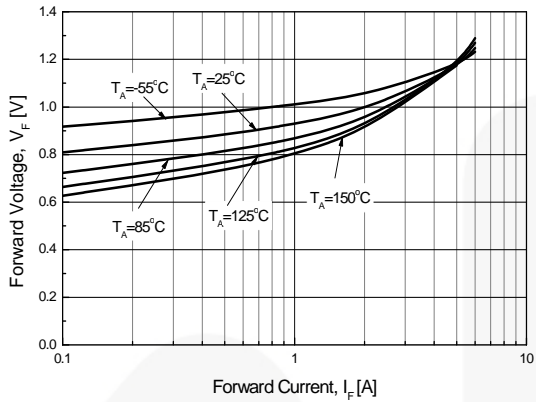


Figure 1. Forward Voltage vs Forward Current (Per diode)

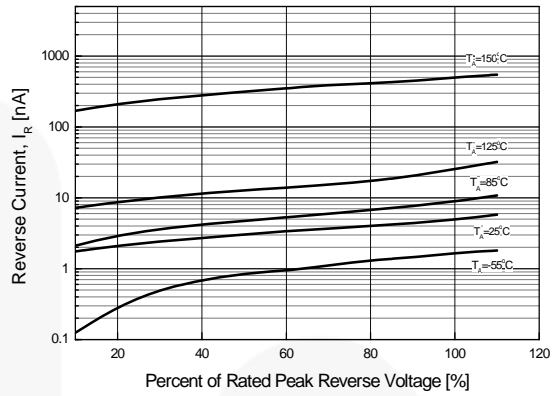


Figure 2. Typical Reverse Current Characteristics (Per Diode)

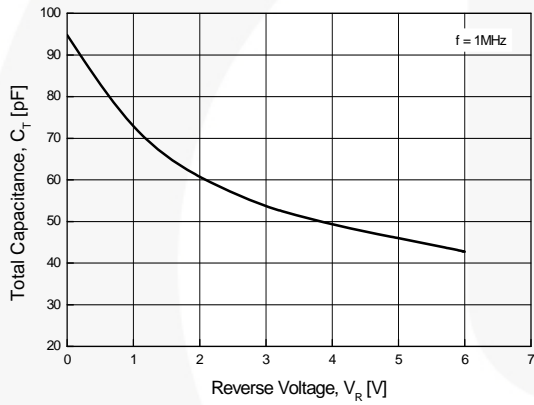
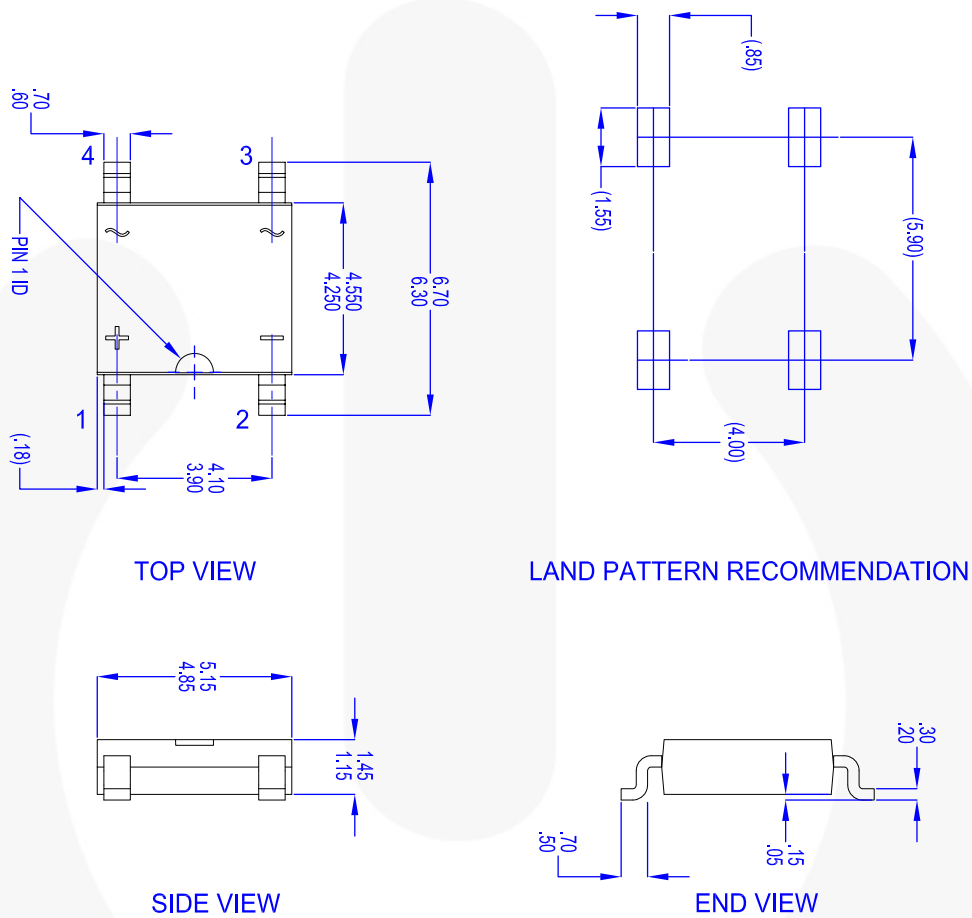


Figure 3. Total Capacitance

Physical Dimension

Micro-DIP



NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY REFERENCE STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- G. DRAWING FILE NAME: MKT-TDI04AREV1.

Figure 4. 4-LEAD, MICRO SURFACE MOUNT, 1.3 x 4 x 5 mm (Active)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.






Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/dwg/TD/TDI04A.pdf>



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™	F-PFS™		Sync-Lock™
AX-CAP®*	FRFET®	PowerTrench®	
BitSiC™	Global Power Resource SM	PowerXS™	TinyBoost®
Build it Now™	GreenBridge™	Programmable Active Droop™	TinyBuck®
CorePLUS™	Green FPS™	QFET®	TinyCalc™
CorePOWER™	Green FPS™ e-Series™	QS™	TinyLogic®
CROSSVOL™	Gmax™	Quiet Series™	TINYOPTO™
CTL™	GTO™	RapidConfigure™	TinyPower™
Current Transfer Logic™	IntelliMAX™		TinyPWM™
DEUXPEED®	ISOPLANAR™	Saving our world, 1mW/W/kW at a time™	TinyWire™
Dual Cool™	Making Small Speakers Sound Louder and Better™	SignalWise™	TranSiC™
EcoSPARK®	MegaBuck™	SmartMax™	TriFault Detect™
EfficientMax™	MICROCOUPLER™	SMART START™	TRUECURRENT®*
ESBC™	MicroFET™	Solutions for Your Success™	μSerDes™
	MicroPak™	SPM®	
Fairchild®	MicroPak2™	STEALTH™	UHC®
Fairchild Semiconductor®	MillerDrive™	SuperFET®	Ultra FRFET™
FACT Quiet Series™	MotionMax™	SuperSOT™-3	UniFET™
FACT®	mWSaver®	SuperSOT™-6	VcX™
FAST®	OptoHiT™	SuperSOT™-8	VisualMax™
FastvCore™	OPTOLOGIC®	SupreMOS®	VoltagePlus™
FETBench™	OPTOPLANAR®	SyncFET™	XS™
FPS™			

* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. I66

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Fairchild Semiconductor:](#)

[MDB6S](#)